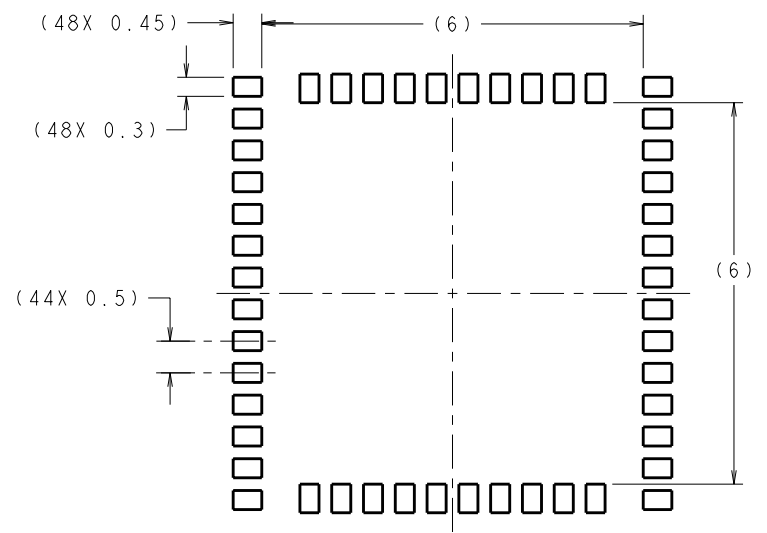
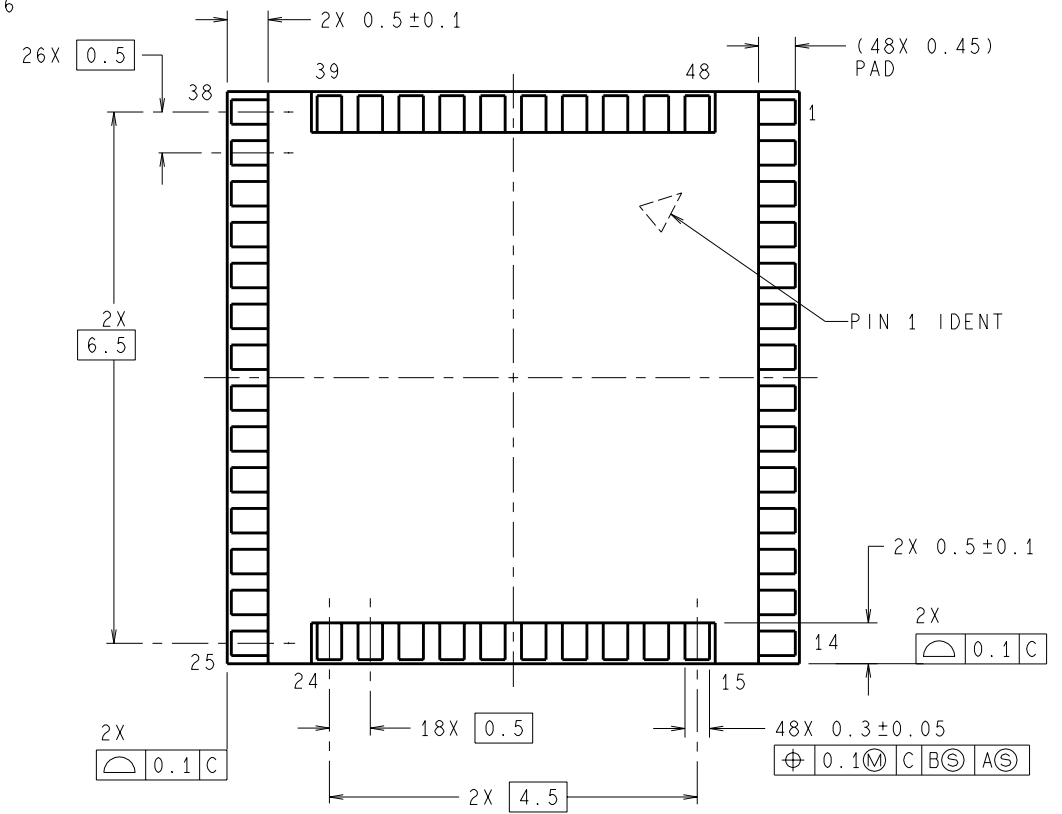
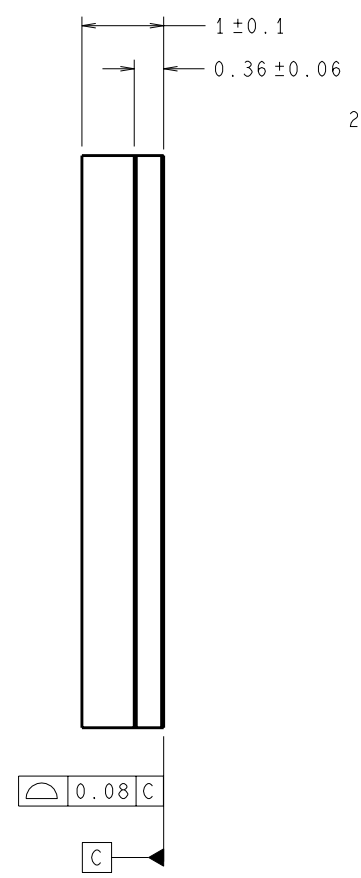
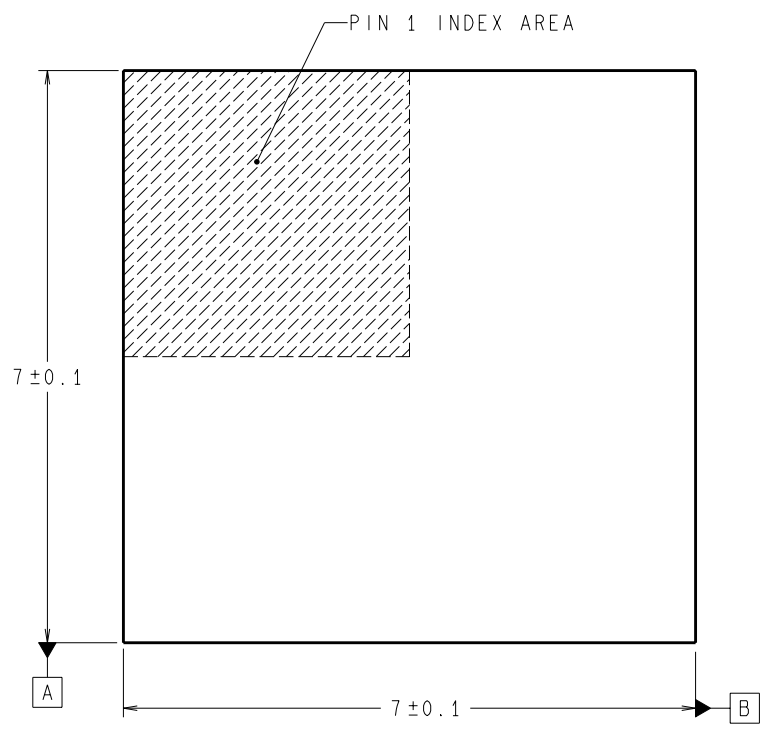


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12450	04/19/2000	TL/WL



RECOMMENDED LAND PATTERN
1:1 RATIO WITH PACKAGE SOLDER PADS

DIMENSIONS ARE IN MILLIMETERS



NOTES: UNLESS OTHERWISE SPECIFIED.

- MATERIAL: BT RESIN CCL-HL832 WITH TAIYO PSR4000 AUS5 SOLDER MASK.
- PLATING: Cu 15 TO 20 MICROMETERS
Ni 10 ± 5 MICROMETERS
Au 1 ± 0.5 MICROMETER
- REFERENCE JEDEC MO-208, VARIATION KKEA, DATED DECEMBER 1999.

APPROVALS	DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	CSP, PLASTIC, LAMINATED, 7 x 7 x 1 mm BODY, 48 L, 0.5 mm PITCH		
DRAWN T. LEQUANG	04/19/2000				
DFTG. CHK. MARTA SUCHY	04/19/2000				
ENGR. CHK. WAYNE LEE	04/19/2000				
 PROJECTION INCH [MM]		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(SC)MKT-SLB48B	A
DO NOT SCALE DRAWING				SHEET 1 of 1	